



Material Content Data Sheet



Sales Product Name		ICL5102		Issued		14. February 2018		
MA#		MA001656936						
Package		PG-DSO-16-23		Weight*		154.66 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.303	2.78	2.78	27822	27822
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		106	
	non noble metal	zinc	7440-66-6	0.066	0.04		424	
	non noble metal	iron	7439-89-6	1.311	0.85		8479	
wire	non noble metal	copper	7440-50-8	53.247	34.43	35.33	344288	353297
	noble metal	gold	7440-57-5	0.728	0.47	0.47	4709	4709
	encapsulation	organic material	carbon black	1333-86-4	0.276	0.18		1783
plastics		epoxy resin	-	8.919	5.77		57667	
	inorganic material	silicondioxide	60676-86-0	82.750	53.50	59.45	535052	594502
leadfinish	non noble metal	tin	7440-31-5	1.530	0.99	0.99	9894	9894
plating	noble metal	silver	7440-22-4	0.226	0.15	0.15	1459	1459
glue	plastics	acrylic resin	-	0.283	0.18		1830	
	noble metal	silver	7440-22-4	1.003	0.65	0.83	6487	8317
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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